

Application No.: 10/707,507

Docket No.: 22171-00011-US

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0025] with the following amended paragraph:

[0025] The circuit board 110 comprises an upper surface 122 and a bottom surface 123, a plurality of testing pads 124 provided on the upper surface 122 for electrical connecting to a test machine directly (not shown in FIG. 3). In addition, the circuit board ~~100~~ 110 can further comprise a plurality of electronic devices 132, such as a capacitor, a resistance, or an inductance, provided on the upper surface 122 for processing testing signal or impedance matching. The testing pads 124 are separated by a second pitch 126, whose size can be designed according to the specification of the test machine. The second pitch 126 separating the testing pads 124 is larger than the first ~~pitch~~ pitch 220 separating the probe 210.

Please replace paragraph [0027] with the following amended paragraph:

[0027] FIG. 5 is a schematic diagram showing the fabrication of the circuit board 110 according to the invention. As shown in FIG. 5, the circuit board ~~100~~ 110 is manufactured by thermally laminating four pieces of laminates 120, 130, 140 and 150. The laminates 120, 130, 140 and 150 can be made of polyimide or FR-4, and a conductive metal 138 is formed inside in advance. The pitch between the conductive metal 138 of the uppermost laminate 120 corresponds to the second pitch 126 separating the testing pads 124, while the pitch between the conductive metal 138 of the bottommost laminate 150 corresponds to the first pitch 220 separating the ~~testing pads~~ probes 210. Although the four pieces of laminates shown in FIG. 5 are used for pitch adjusting, impedance matching, anti-reflection, anti-degenerating and anti-disturbance, one skilled in the art should appreciate that the invention can use laminates other than four pieces for pitch adjusting and impedance matching. After the laminates 120, 130, 140 and 150 are completed, a thermal laminating process is performed to laminate the pieces 120, 130, 140 and 150 into the circuit board ~~100~~ 110, wherein the conductive metal 138 in each laminate consists of the conductive wire 128 of the circuit board 110.